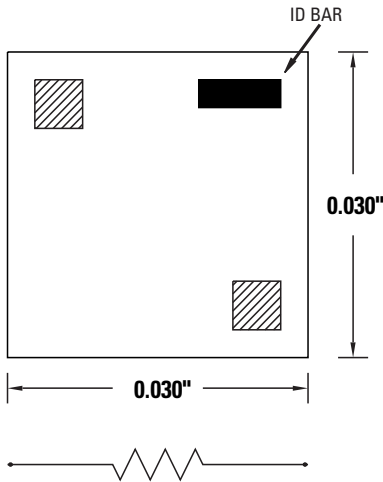


MSSR SERIES

MSSR-3

MSSR-3



SIZE 0.030" x 0.030" x 0.010" (± 0.003 ")
 RESISTANCE RANGE 2 Ω TO 3M Ω
 NUMERIC LASER CODE. CONSULT SALES FOR DETAILS

COMMON SERIES DATA

SUBSTRATE MATERIAL	SILICON
BOND PADS	GOLD (15,000 Å MIN.), OPTIONAL: ALUMINUM (10,000 Å MIN.)
BACKSIDE SURFACE	BARE OR GOLD BACK OPTIONAL
TOLERANCES	0.01%, 0.05%, 0.1%, 0.5%, 1%, 2%, 5%, 10%, 20%
T.C.R.	
NICHROME	± 25 ppm/ $^{\circ}$ C STANDARD; OPTIONAL TO ± 5 ppm/ $^{\circ}$ C
TANTALUM NITRIDE	± 150 ppm/ $^{\circ}$ C STANDARD; OPTIONAL TO ± 10 ppm/ $^{\circ}$ C
CURRENT NOISE	-20dB
DIELECTRIC BREAKDOWN	400 V MIN.
INSULATION RESISTANCE	10 12 Ω MIN.
OPERATING VOLTAGE	100 V MAX.
POWER RATING	250 mW (70 $^{\circ}$ C DERATED LINEARLY TO 150 $^{\circ}$ C) $P = E^2 / R$
SHORT TERM OVERLOAD	5X RATED POWER, 25 $^{\circ}$ C, 5 SEC., ± 0.25 % MAX. $\Delta R/R$
HIGH TEMP EXPOSURE	150 $^{\circ}$ C, 100 HRS., ± 0.25 % MAX. $\Delta R/R$
THERMAL SHOCK	MIL-STD 202, METHOD 107F, ± 0.25 % MAX. $\Delta R/R$
MOISTURE RESISTANCE	MIL-STD 202, METHOD 106, ± 0.5 % MAX. $\Delta R/R$
STABILITY	1000 HRS., 70 $^{\circ}$ C, 125mW, ± 0.5 % MAX. $\Delta R/R$
OPERATING TEMP RANGE	-55 $^{\circ}$ C TO +150 $^{\circ}$ C
STRAY DISTRIBUTED CAPACITANCE	
SILICON	2pF

PART NUMBER DESIGNATION

MSSR 3	S	X	XXXXX	X	X
SERIES	SUBSTRATE	RESISTIVE FILM	OHMIC VALUE	TOLERANCE	OPTION DESIGNATOR (If Required)
3	S = Silicon	N = Nichrome T = Tantalum Nitride	5-Digit Number: 1st 4 Digits Are Significant With "R" As Decimal Point When Required. 5th Digit Represents Number of Zeros.	S = 0.01% Q = 0.05% B = 0.1% D = 0.5% F = 1% G = 2% J = 5% K = 10% M = 20%	A = ± 50 ppm/ $^{\circ}$ C B = ± 25 ppm/ $^{\circ}$ C C = ± 10 ppm/ $^{\circ}$ C D = ± 5 ppm/ $^{\circ}$ C E = Aluminum Bond Pads GB = Gold Backside F = ± 100 ppm/ $^{\circ}$ C G = Gold Bond Pads (Always used when no other option is required)

EXAMPLES: MSSR 3SN-50R00F-GB = 0.020" x 0.020", Silicon Substrate, Nichrome Resistor, 50 Ω , ± 1 % Tol., Gold Backside.